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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

1. Name of conveying party(ies):

**Jae Suk LEE**

Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies)

Name: DongbuAnam Semiconductor Inc.

Internal Address: \_\_\_\_\_

Street Address: \_\_\_\_\_

891-10, Daechi-Dong  
Kangnam-Ku

City: Seoul

Country: Republic of Korea

Zip: \_\_\_\_\_

Additional name(s) & address(es) attached:  Yes  No

3. Nature of Conveyance:

Assignment  Merger  
 Security Agreement  Change of Name  
 Other \_\_\_\_\_

Execution Date: December 20, 2005

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the new application is: December 20, 2005

A. Patent Application No.(s): ; filed

B. Patent No.(s):

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Song K. Jung  
MCKENNA LONG & ALDRIDGE LLP  
Internal Address: Atty. Dkt.: 10216.085.00-US  
Street Address: \_\_\_\_\_

1900 K STREET, N.W.

City: WASHINGTON State: DC Zip: 20006

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) \$ 40.00

Enclosed  
 Authorized to be charged to deposit account  
 Authorized to be charged to credit card  
(Form 2038 enclosed)

8. Deposit account number:

50-0911

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9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Mark R. Kresloff; Reg. No. 42,766  
Name of Person Signing

[Signature]  
Signature

December 21, 2005  
Date

Total number of pages including cover sheet, attachments, and documents: 3

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113002 U.S. PTO  
11/312353

122105

Docket No.: 10216.085.00

## Assignment of Application

<b>WHEREAS, I (WE)</b>	Jac Suk LEE
, respectively,	
have invented certain new and useful improvements in:	
<b>METHOD FOR FORMING METAL LINE OF SEMICONDUCTOR DEVICE</b>	
for which an application for Letters Patent was executed on	

(Application No.		, Filed		), and
<b>WHEREAS,</b>	<b>DongbuAnam Semiconductor Inc.</b>			
(hereinafter referred to as "ASSIGNEE") having a place of business at: 891-10, Daechi-Dong, Kangnam-Ku, Seoul, Korea				

is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;

NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), the receipt whereof is hereby acknowledged, and for other good and valuable consideration, I (WE), by these presents do sell, assign and transfer unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters patent which may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in and to any and all divisions, reissues, continuations, substitutions and renewals thereof.

I (WE) hereby authorize and request the Patent Office Officials in the United States and its territorial possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the assignee of my (our) entire right, title and interest in and to the same, for the sole use and behalf of said ASSIGNEE, its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and entirely as the same would have been held by me (us) had this Assignment and sale not been made.

Further, I (WE) agree that I (WE) will communicate to said ASSIGNEE or its (his) representatives any facts known to me (us) respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letters Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and

enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

The undersigned hereby grant(s) the firm of McKenna Long & Aldridge LLP, Attorneys at Law, 1900 K Street, N.W., Washington, D.C. 20006 the power to insert on this assignment any further identification, including the application number and filing date, which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: 2005. 12. 20

JAE SUK LEE  
(Signature of Inventor)  
Jae Suk LEE

**McKenna Long & Aldridge LLP**  
Attorneys At Law  
1900 K Street, N.W.  
Washington, D.C. 20006